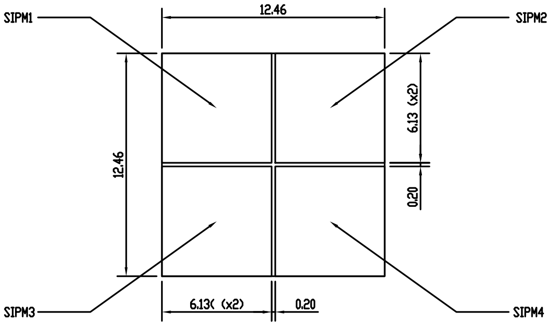
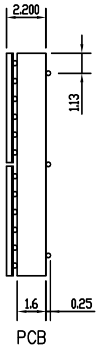
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ARRAYJ–600XX–4P
CASE 100DL
ISSUE O

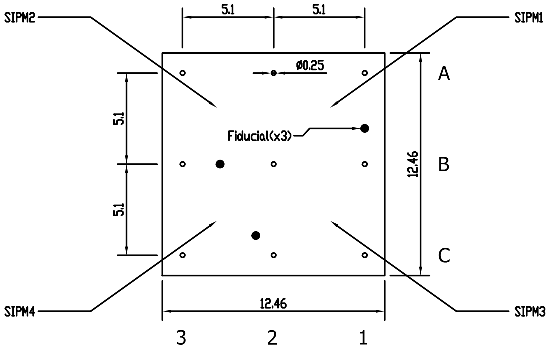
DATE 31 JUL 2018



Top View Scale 5 : 1



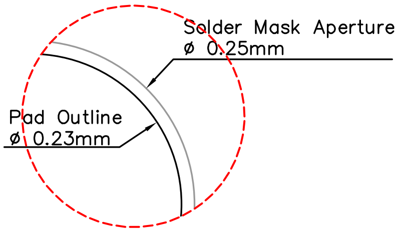
Side View Scale 5 : 1



Bottom View Scale 5 : 1

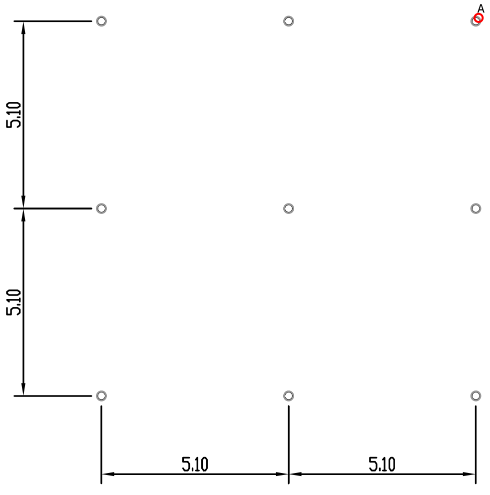
All Dimensions ± 0.1mm Unless Otherwise Stated

Solder Bump Assignments	
Bump #	Function
A1	Anode 1
A2	Anode 2
A3	Common Cathode
B1	Anode 3
B2	Anode 4
B3	Common Cathode
C1	Common Cathode
C2	Common Cathode
C3	Common Cathode



Zoom View A

NOTE
Solder pads may be oversized to ease placement of the array on the carrier PCB. Consult with contract manufacturer for recommenation based on placement accuracy capability.



Recommended PCB Solder Footprint
Scale 10:1

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